

Electronic Patent Application Fee Transmittal

Application Number:	10539735			
Filing Date:	20-Jun-2005			
Title of Invention:	SURFACE-MOUNTED MICROWAVE PACKAGE AND CORRESPONDING MOUNTING WITH A MULTILAYER CIRCUIT			
First Named Inventor/Applicant Name:	Phillippe Kertesz			
Filer:	Kenneth M. Berner/Candace Chambliss			
Attorney Docket Number:	4590-426			
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U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
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Claims:				
Miscellaneous-Filing:				
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Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1510	1510
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Total in USD (\$)				1810